



Europäisches Patentamt
European Patent Office
Office européen des brevets



(11) **EP 1 387 374 B9**

(12) **CORRECTED EUROPEAN PATENT SPECIFICATION**

Note: Bibliography reflects the latest situation

(15) Correction information: **Corrected version no 1 (W1 B1)**
Corrections, see page(s) 4-8

(51) Int Cl.: **H01H 13/70** ^(1968.09)

(48) Corrigendum issued on:
05.04.2006 Bulletin 2006/14

(45) Date of publication and mention
of the grant of the patent:
26.10.2005 Bulletin 2005/43

(21) Application number: **03017231.6**

(22) Date of filing: **30.07.2003**

(54) **Key pad, resin key top injection mold, and resin key top manufacturing method**

Tastatur, Spritzgussverfahren für einen Harztastenkopf und Gussform

Clavier, moule d'injection pour un bouton poussoir en résine et son procédé de fabrication

(84) Designated Contracting States:
DE FI GB SE

(30) Priority: **02.08.2002 JP 2002226675**

(43) Date of publication of application:
04.02.2004 Bulletin 2004/06

(73) Proprietor: **POLYMATECH CO., LTD.**
Chuo-Ku,
Tokyo (JP)

(72) Inventor: **Yamauchi, Motoshi,**
Technical Center of Polymatech
Iwatuki-shi,
Saitama-prefecture (JP)

(74) Representative: **Lorenz, Werner**
Lorenz & Kollegen,
Alte Ulmer Strasse 2
89522 Heidenheim (DE)

(56) References cited:
DE-A- 10 028 222 **DE-U- 20 117 019**
JP-A- 2002 052 566 **US-A- 4 670 633**

EP 1 387 374 B9

Note: Within nine months from the publication of the mention of the grant of the European patent, any person may give notice to the European Patent Office of opposition to the European patent granted. Notice of opposition shall be filed in a written reasoned statement. It shall not be deemed to have been filed until the opposition fee has been paid. (Art. 99(1) European Patent Convention).

Description

BACKGROUND OF THE INVENTION

1. Field of the Invention

[0001] This invention relates to a key pad suitable as a push-button switch component to be incorporated in the input portion of an electronic apparatus, such as a telephone, an audio apparatus, a television set, a VCR, a facsimile apparatus, a copying machine, or a vehicle-mounted apparatus, and, in particular, to a key pad, which is suitable as the push-button switch component of a portable apparatus of which a reduction in thickness and size is required. Further, this invention relates to a resin key top injection mold and a resin key top manufacturing method.

2. Related Background Art

[0002] DE 201 17 019 U1 describes a key top with a hole and an LED being arranged underneath the key top so that one LED is provided in correspondence with one key top. With the hole being formed in the key top and the LED being lighted from within hole, this construction requires, rather than illuminating the key top, that bright light be emitted to the exterior while avoiding the areas of the translucent key tops.

[0003] From US 4,670,633 there is known a keyboard capable of efficiently illuminating push buttons with a small number of light sources. The keyboard comprises a plurality of pyramidal reflectors for reflecting light to the sides of the push buttons.

[0004] JP 2002/052566 A discloses a method for molding a key top in which characters and patterns printed on a base material are not deformed by molding.

[0005] A key top mold is described in DE 100 28 222 A1, which comprises moving cores located in cavities of the mold.

[0006] Up to now, an illumination type key pad equipped with a translucent elastic key sheet and a translucent resin key top has been widely used as a push-button switch component to be incorporated in the input portion of a portable apparatus, such as a mobile phone. Fig. 12 shows a specific example of such a key pad. In the drawing, a key pad 1 is composed of a key sheet 2 obtained through molding of translucent silicone rubber or translucent thermoplastic elastomer into a sheet, and resin key tops 3 obtained through injection molding of a translucent thermoplastic resin into buttons and firmly attached to the key sheet 2 through the intermediation of translucent adhesive layers 4. This key pad 1 is placed on a substrate surface 7a having thereon disc springs 5, chip components 6 with LEDs or the like serving as the illumination sources, etc., and is integrated with a substrate 7, etc. to form a push-button switch for input operation.

[0007] In many cases, each resin key top 3 in such a

push-button switch has at the outer periphery of the lower end of its side surface an outwardly protruding flange portion 8. This flange portion 8 is adapted to engage with the back surface of a casing 9 to prevent the key top from being detached from the apparatus (casing 9). Further, when the LEDs or the like incorporated in the chip components 6 are caused to emit light to illuminate the resin key tops from within the casing 9, leakage of light through the gaps between the resin key tops 3 and the casing 9 can be prevented by equipping the flange portions 8 with shielding layers, thereby enhancing the illumination property for the resin key tops 3.

[0008] Generally speaking, there is a requirement for a further reduction in the thickness and size of portable apparatuses, such as mobile phones. In view of this, in the key pad 1 as shown in Fig. 12, a further reduction in the thickness and size of the components including the key sheet 2, the resin key tops 3, and the adhesive layers 4 is being contemplated. However, a further reduction in the thickness and size of the key pad would result in a reduction in the interval between the resin key tops 3 facing each other and a reduction in the vertical distance between the resin key tops 3 and the substrate 7. Thus, it has been concluded that the flange portions 8 of the resin key tops 3 would inevitably come into contact with the chip components 6 protruding from the substrate surface 7a.

[0009] It might be possible to avoid this problem of contact, for example, by reducing the number of chip components 6. However, that would result in some of the resin key tops 3 not being sufficiently illuminated, making it impossible to uniformly and sufficiently illuminate all the resin key tops 3. It might also be possible to reduce the size of the resin key tops 3. However, that would involve a deterioration in the depression-operability of the resin key tops 3, resulting in a rather inaccurate input operation, which is inconvenient for the user.

[0010] In this regard, the present inventor considered a method of partially trimming the flange portions 8 of the resin key tops 3. However, as shown in Fig. 13, with the method in which the flange portions 8 are partially trimmed by a trimming die after the molding of the resin key tops 3, the cutting edges a through c are likely to involve positional variation, so that the width dimensions of the remaining flange portions 8 are rather varied, resulting in frequent occurrence of light leakage at the time of illumination. In particular, the resin key tops of a portable apparatus which is generally very small in total size are subject to such variation in the cutting edges a through c.

SUMMARY OF THE INVENTION

[0011] As described above, the present invention has been made after examining the way to avoid the problem of contact involved when the conventional key pad 1 is to be reduced in thickness and size. It is accordingly an object of the present invention to provide a key pad for

use in a portable electronic apparatus or the like in which the resin key tops and the chip components such as LEDs do not come into contact with each other, which eliminates light leakage at the time of illumination, and in which the resin key tops are not easily detached from the apparatus.

[0012] Further, the present invention also aims to provide a resin key top for use in such a key pad, an injection mold for this resin key top, and a resin key top manufacturing method.

[0013] To achieve the above objects, there is provided, in accordance with the present invention, a key pad according to claim 1.

[0014] In accordance with this invention, the resin key tops have in their side surfaces clearance portions of a configuration in conformity with the outer configuration of interference members at least the upper portions of which are situated in displacement regions at the bottom surface edges of the resin key tops allowing their displacement when they are depressed, so that the resin key tops do not come into contact with the interference members whether the key tops are being depressed for input operation or not being depressed. Thus, it is possible to cope with the reduction in the distance between the side surfaces of the resin key tops and the reduction in the vertical distance between the resin key tops and the substrate due to the reduction in thickness and size. In particular, in the case of a key pad in which the resin key tops have on their side surfaces outwardly protruding flange portions with clearance portions formed therein, there is practically no fear of light being leaked through the gaps between the apparatus casing and the resin key tops when the back lights are on. Thus, such a resin key top with a clearance portion is capable of coping with a reduction in the thickness and size of the apparatus and is optimally applicable to an illumination type key pad and resin key tops used therein.

[0015] The above-mentioned interference member is the portion which would come into contact with the resin key top upon depression of the resin key to thereby hinder the descent of the resin key top were it not for the clearance portion in the resin key top. In many cases, it is composed of a "protrusion" from a general surface of a surface of the key sheet; in some cases, it may be a leg portion or the like floatingly supporting the resin key top mounting portion of the key sheet so as to be capable of moving toward and away from the substrate surface opposed to the key sheet back surface. Further, the above-mentioned "protrusion" means an element protruding from the key sheet surface; it is a term covering both the key sheet itself and an object other than the key sheet. Specifically speaking, first, it means a circuit component connected to the substrate circuit in a protruding state with respect to the substrate surface opposed to the key sheet back surface. As stated above, the recent tendency toward a reduction in the thickness and size of portable apparatus is remarkable. However, there are limitations to a reduction in the thickness and size of the

chip component such as LED, i.e., the circuit component itself, and a reduction in the vertical distance between it and the resin key top is inevitable. As a result, the circuit component has to protrude from a general surface of the key sheet surface through an insertion hole formed in the key sheet. In the present invention, however, it is possible, also in such a case, to avoid the above-mentioned contact due to the clearance portion of the resin key top. Further, the key sheet is often equipped with an "accommodating portion" for protecting such a circuit component. As a second specific example of what is implied by the term "protrusion", this "accommodating portion" is adopted. In some cases, regardless of whether the circuit component protrudes from the general surface of the key sheet or not, the accommodating portion is formed so as to protrude from the general surface. In particular, when the key sheet is to be perfectly waterproof and dust-proof, it protrudes from the general surface of the key sheet in a dome-like or box-like fashion to perfectly cover the circuit component. When such a waterproof and dust-proof property is not required, the accommodating portion is formed so as to protrude upwards in a cylindrical form from the sheet. Then, in the present invention, it is possible, in either case, to prevent the resin key top from coming into contact with the accommodating portion.

[0016] Further, this key pad is applicable to both of the following cases: the case in which, if there is no clearance portion, the side surface of the resin key top does not overlap the interference member when the key top is not being depressed for input, whereas when it is being depressed for input operation, the side surface of the resin key top overlaps the interference member, and the case in which the side surface of the resin key top overlaps the interference member whether it is being depressed or not. Thus, in either case, it is possible to prevent the resin key top from coming into contact with the interference member.

[0017] Further, the "clearance portion" of the resin key top may be of a configuration in which the wall thickness is entirely reduced along the height direction of the portion of the resin key top (e.g., the flange portion) where it is formed, or of a configuration in which the wall thickness is reduced only in the lower portion along the height direction thereof. Further, the term "conformity" does not imply that the configuration of the clearance portion perfectly coincides with the outer configuration of the interference member; it is only necessary for the resin key top to be capable of avoiding contact with the interference member, so that it suffices for their configurations to be substantially in conformity with each other. For example, when the outer configuration of the interference member is polygonal in section, the configuration of the clearance portion may be of an arcuate one with a radius of curvature somewhat larger than the circumscribed thereof.

[0018] Claims 3 and 4 describe alternative resin key tops.

[0019] Further, in accordance with the present invention, there is provided a resin key top injection mold ac-

ording to claim 5.

[0020] In this resin key top injection mold, the runner portion communicating with the key top forming portion, is provided in the cavity. Further, in the cavity, there is provided the resin relief protrusion having a molding surface swollen from the entrance of the key top forming portion and the runner portion toward the key top forming portion, with the molding surface being smaller in width than the entrance and of a configuration in conformity with the outer configuration of the interference member at least the upper portion of which is situated in the displacement region of the bottom surface edge of the resin key top to be displaced upon a depressing operation. Thus, solely by the runner portion cutting off process, it is possible to easily form a clearance portion of a configuration in conformity with the outer configuration of the interference member, which is of, e.g., a V-shaped or arcuate configuration, on the resin key top and a part of the flange portion thereof. Further, since the resin relief protrusion is smaller in width than the entrance, it is possible for a molten resin to flow without allowing any air to be gathered on either side of the resin relief protrusion, making it possible to obtain a resin key top superior in dimensional performance and quality and a key pad using the same.

[0021] Further, this injection mold can be formed as one with pin holes allowing detachable attachment of a plurality of pin members constituting resin relief protrusions and differing in molding surface configuration. By thus forming pin holes allowing detachable attachment of a plurality of pin members differing in molding surface configuration, quick adaptation to a product with an interference member having a different outer surface configuration is possible solely by replacing the pin members without involving any remodeling of the mold itself, making it possible to obtain a resin key top injection mold superior in product compatibility.

[0022] Further, in a resin key top injection mold the entrance of which is wider on the key top forming portion side and narrower on the runner portion side, flow of a molten resin into the cavity takes place quickly, and it is possible to reduce or eliminate an occurrence of air gathering. Further, in a resin key top injection mold with an air vent portion communicating with a part of the runner portion, it is possible to eliminate any generation of flow marks on the resin key tops.

[0023] The present invention further provides a resin key top manufacturing method according to claim 10.

[0024] In this resin key top manufacturing method, it is possible to easily form a clearance portion of a configuration in conformity with the outer configuration of the interference member on a part of the flange portion through a normally conducted runner portion eliminating process without adding any surplus step to the conventional resin key top manufacturing process. Further, since a molten resin is poured into the cavity of the injection mold having the runner portion and the resin relief protrusion, the clearance portion formed on the resin key

top through molding can be reliably in a configuration in conformity with the outer configuration of the accommodating portion of the key sheet and no defective molding due to an occurrence of gathering of air or the like is involved. Further, generation of flow marks on the resin key top is prevented, and it is possible to obtain a high quality resin key top in which, even if an indicating portion having a character, symbol or the like thereon is provided on the back side of the resin key top, the indicating portion is not distorted by flow marks.

[0025] The above descriptions of this invention should not be construed restrictively. The objects, advantages, features, and uses of this invention will be made more apparent from the following description given with reference to the accompanying drawings. Further, it should be understood that all appropriate modifications not departing from the scope of the gist of this invention are covered by this invention.

BRIEF DESCRIPTION OF THE DRAWINGS

[0026] In the accompanying drawings:

Fig. 1 is a sectional view taken along the line 1-1 of Fig. 2, showing a key pad according to an embodiment of the present invention;

Fig. 2 is an enlarged plan view of a key pad according to an embodiment of the present invention, showing the portion 2 of Fig. 3;

Fig. 3 is a partial enlarged plan view of the input portion of a mobile phone using a key pad according to an embodiment of the present invention;

Fig. 4 is a sectional view of a key pad according to another embodiment of the present invention;

Fig. 5 is a sectional view taken along the line 5-5 of Fig. 6, showing a main parts of a resin key top injection mold according to an embodiment of the present invention;

Fig. 6 is a transparent plan view of a main parts of a resin key top injection mold according to an embodiment of the present invention;

Fig. 7 is a transparent plan view of a main parts of a resin key top injection mold according to another embodiment of the present invention;

Fig. 8 is a transparent plan view of a resin key top injection mold according to another embodiment of the present invention;

Fig. 9 is a transparent plan view of a resin key top injection mold according to another embodiment of the present invention;

Fig. 10 is a longitudinal sectional view of a resin key top injection mold according to another embodiment of the present invention;

Fig. 11 is a transparent plan view of an example of a main parts of a resin key top injection mold different from that of the present invention;

Fig. 12 is a longitudinal sectional view of a conventional key pad; and

Fig. 13 is an explanatory drawing, a plan view of a resin key top, illustrating how difficult it is to work on a resin key top after molding.

DESCRIPTION OF THE PREFERRED EMBODIMENTS

[0027] Embodiments of the present invention will now be described in detail with reference to the drawings.

[0028] A key pad 11 according to an embodiment of the present invention will be described with reference to Figs. 1 through 3. Fig. 2 is a partial enlarged view of a portion 2 of a key pad to be used in a mobile phone as shown in Fig. 3, and Fig. 1 is a sectional view taken along the line 1-1 of Fig. 2. As shown in Fig. 1, the key pad 11 of this embodiment has a flexible key sheet 12 formed of translucent silicone rubber, thermoplastic elastomer, or the like, and resin key tops 13 obtained by molding translucent thermoplastic resin and fixed to the key sheet through the intermediation of a translucent adhesive layer 14. Then, the key pad 11 is placed on a substrate 17 having contact switches 15 and a chip component 16 consisting of an LED or the like serving as the illumination source. The resin key tops 13 and the circuit (not shown) on the substrate 17 are reduced in thickness and size as compared with those in the prior art, and the chip component 16 containing a component such as an LED in the form of a package that cannot be directly incorporated in the substrate circuit protrudes from the substrate surface 17a and is connected to the substrate circuit. Thus, formed in the key sheet 12, formed so as to cover the substrate 17, is an accommodating portion 19 in the form of a box covering the chip component 16 and protruding from a general surface 12a constituting the surface of the key sheet 12, with the accommodating portion 19 constituting an "interference member" (or "protruding member"). Further, the distance between the resin key tops 13 is reduced as compared with that in the prior art, so that clearance portions 20 of a configuration in conformity with the outer configuration of the accommodating portion 19 and keeping them out of contact therewith are formed on flange portions 18 serving as the "side surfaces" of the resin key tops 13 opposed to the accommodating portion 19 serving as the "interference member" (or the "protruding member"). In other words, the flange portions 18 have the clearance portions 20 of a configuration in conformity with the outer configuration of the accommodating portion 19. Thus, in this embodiment, if the clearance portions 20 were not provided, the flange portions 18 serving as the "side surfaces" of the resin key tops 13 and the accommodating portion 19 would overlap each other in the height direction when no depressing operation for input is being performed.

[0029] While in this embodiment the accommodating portion 19 is formed based on the size of the chip component 16, it is also possible to form the accommodating portion 19 based on the sizes of the various elements, components, wiring, etc. other than the chip component

16. It is also possible for the accommodating portion 19 to be formed as a cylinder with its upper end open or in a "leg-less" configuration in which the portion thereof extending downwards from the back surface of the key sheet 12 to the substrate surface 17a is omitted. Further, when the chip component 16 is high enough to extend beyond the general surface 12a of the key sheet 12, it is possible to form an insertion hole in the key sheet 12, with the high chip component protruding therefrom. In this case, the chip component constitutes the "protruding member". Further, as shown in Fig. 4, it is also possible to adopt a construction in which the general surface 12a of the key sheet 12 is flat and in which the accommodating portion covering the chip component 16 consists of a leg portion 17c floatingly supporting the portions of the key sheet 12 mounted to the resin key tops 13 such that they can move toward and away from the substrate surface 17a opposed to the key sheet back surface 12b. In this case, the leg portion 17c constitutes the interference member.

[0030] The resin key tops 13 of this embodiment are preferably formed of a translucent resin which allows light to be transmitted therethrough. Examples of the resin for the resin key tops 13 include polycarbonate resin, polymethyl methacrylate (PMMA) resin, polystyrene (PS) resin, acrylonitrile-styrene (AS) copolymer, methyl methacrylate-styrene (MS) copolymer, and polyethylene (PE) type resin. From the viewpoint of translucency, wear resistance, etc., polycarbonate resin is preferable. Note that in this specification the term "translucent" refers to a visible light transmission of 0.1% or more. When the visible light transmission is 0.1% or more, the surface of the resin key top 13 is perceived as illuminated when the back light consisting of an LED or the like is lighted.

[0031] The key sheet 12 of this embodiment is preferably formed of silicone rubber, which is a translucent and flexible rubber-like elastic material, thermoplastic elastomer, or the like. For, the key sheet 12 must be as follows: when the resin key top 13 is depressed, it is deflected to turn ON the contact switch 15, whereas, when the depression is canceled, it is restored to the initial position. Further, the reason for adopting a translucent rubber-like elastic material is that, in the case of the illumination type key pad 11, it is necessary for light to be transmitted through the key sheet 12.

[0032] The adhesive layer 14 of this embodiment consists of a translucent adhesive which is capable of gluing the resin key tops 13 and the key sheet 12 to each other. More specifically, it is an adhesive of cold setting type, ultraviolet setting type, etc. It is possible to adopt various types of adhesive including urethane type and acrylic type ones. The adhesive layer 14 prevents the resin key tops 13 from falling out of the casing 21. The flange portions 18 of the resin key tops 13 are engaged with the casing 21, so that, in some cases, the resin key tops 13 need not be glued to the key sheet 12.

[0033] Regarding the chip component 16 having an illumination source such as an LED with light emitting

function, the substrate 17, etc., they may consist of ordinary members for use in the push-button switch of a portable apparatus or the like.

[0034] Next, a method of manufacturing the resin key tops 13 according to an embodiment of the present invention will be described.

[0035] First, a mold for injection molding of molten resin is prepared. This mold is composed of first and second molds.

[0036] As shown in Figs. 5 and 6, the first mold 31 is the mold for molding the front side of the resin key top 13. It has a recess which defines a cavity composed of a first runner portion 33, a key top forming portion 34, and a second runner portion 35 when the first mold 31 is mated with the second mold 32.

[0037] The first runner portion 31 communicates with a resin injection hole 36 provided in the second mold 32, and constitutes the "upstream side runner portion" serving as a flow passage for molten resin leading to the key top forming portion 34. The key top forming portion 34 is the portion which gives the resin key top 13 after the releasing and the cutting off of unnecessary portions, and which includes a flange portion 39.

[0038] The second runner portion 35 is the portion which collects overflowing resin so that molten resin may sufficiently fill the key top forming portion 34, and which constitutes the "downstream side runner portion" communicating with an air vent portion 37 formed in the second mold 32. The second runner portion 35 is diagonally formed with respect to the first runner portion 33 with the key top forming portion 34 being therebetween. Further, in the entrance (boundary) 40 of the key top forming portion 34 (inclusive of the flange portion 39) and the second runner portion 35, there is formed, substantially at the center thereof, a resin relief protrusion 38 protruding from the cavity surface of the first mold 31 to the surface of the second mold 32, with the resin relief protrusion being in the form of a cylinder vertically extending inside the cavity. This resin relief protrusion 38 has a molding surface 38a expanded at the entrance 40 toward the key top forming portion 34 (39) side and narrower than the entrance 40. Further, it has a configuration such that it is in conformity with the outer configuration of the accommodating portion 19 of the key sheet 12 opposed to the molded resin key top 13. That is, a part of the cross-sectional configuration of the resin relief protrusion is in conformity with the outer configuration of the accommodating portion 19 serving as the "interference member". Further, the entrance 40 is formed so as to be wider on the key top forming portion 34 side and narrower on the second runner portion 35 side.

[0039] As shown in Fig. 5, the second mold 32 is the mold for molding the back side of the resin key top 13, and is equipped with the resin injection hole 36 serving as the gate for supplying molten resin to the first runner portion 33 and the air vent portion 37 for effecting air venting from the second runner portion 35, with the cavity surface being formed as a flat surface.

[0040] The first mold 31 and the second mold 32 of this embodiment are as described above. As shown in Fig. 7, in addition to the second runner portion 35a provided diagonally with respect to the first runner portion 33, it is also possible to provide another second runner portion 35b in a corner adjacent to the first runner portion 33. This type of mold is used, for example, when manufacturing the resin key top 13 marked with the number "8" as shown in Fig. 3. Further, when forming a key pad in which the interference member faces not a corner but a side surface of the resin key top, it is possible to provide the runner portion not in a corner but on a side portion of the resin key top (not shown).

[0041] Further, as shown in Fig. 8, by slightly modifying the configuration of the second runner portion, it is possible to form molded pieces constituting two key tops 13 by means of a mold 31 with cavities arranged symmetrically in the horizontal direction. Further, it is also possible to modify the mold 31 of Fig. 8 into one which is also symmetrical in the vertical direction to realize a four-piece mold (not shown) in which four cavities are arranged around the common air vent portion 37. Further, as shown in Fig. 9, it is also possible to realize a mold in which a common first runner portion 33 is provided for two key top forming portions 34 and in which molten resin flows into the two key top forming portions 34 through the single resin injection hole 36. With this mold, it is possible to reduce the number of resin injection holes 36 with respect to the resin key tops 13 to be obtained, thereby facilitating and expediting the resin pouring operation and reducing the amount of resin accumulated in the first runner portion 33 to be disposed of.

[0042] The configurations of the first runner portion 33 and the second runner portion 35 are not restricted to those shown in the drawings described above. It is also possible to partially equip the first runner portion 33 and the second runner portion 35 with recesses in the form of liquid reservoirs or the like into which resin flows. Further, it is also possible to form the resin relief protrusion 38 on the first runner portion 33 side instead of on the second runner portion 35 side.

[0043] Further, while in the above embodiment the resin relief protrusion 38 is formed in the first mold 31 itself, it is also possible to prepare a molding pin 41 serving as the "pin member" having a molding surface corresponding to the sectional configuration and size of the clearance portion 20 so that the clearance portion 20 can be easily formed in correspondence with changes in configuration and size due to use of a different chip component 16, and to form in the first mold a pin insertion hole 42 allowing attachment of the molding pin 41 as shown in Fig. 10, forming the resin relief protrusion 38 by fitting this molding pin 41 into the first mold. The material of this molding pin 41 preferably consists of a hardened iron material or the like.

[0044] When using the first mold 31 and the second mold 32 as described above, the molds 31 and 32 are mated with each other, and then molten resin is poured

through the resin injection hole 36. The injected molten resin flows from the first runner portion 33 to the key top forming portion 34 including the flange portion 39, and then to the second runner portion 35. At this time, there protrudes from the cavity surface of the first mold 31 in a column-like fashion the resin relief protrusion 38 so as to extend through the entrance 40 of the key top forming portion 34 and the second runner portion 35 to about the second mold 32, exhibiting a molding surface expanding toward the key top forming portion 34 side, being narrower than the entrance and of a configuration in conformity with the outer configuration of the key sheet accommodating portion 19, so that molten resin flows on both sides of the resin relief protrusion 38 through the entrance 40 to flow into the second runner portion 35. Thus, there is no fear of air being gathered so as to generate an irregularly shaped portion in the molded piece, making it possible to fill the cavity evenly with molten resin. When the filling of the cavity with molten resin has been completed, the injection of molten resin is stopped, and the mold is cooled to solidify the molten resin. Thereafter, releasing is performed, whereby a molded piece is obtained in which the portion corresponding to the resin relief protrusion 38 constitutes a substantially disc-like cutout with a substantially semi-circular portion of a configuration in conformity with the outer configuration of the key sheet accommodating portion 19.

[0045] The portions corresponding to the first runner portion 33 and the second runner portion 35 are removed from this molded piece by using a cutting die, whereby the resin key top 13 having the clearance portion 20 in the flange portion 18 thereof is obtained.

[0046] The obtained resin key top 13 is joined to the key sheet 12 by adhesive, whereby the key pad 11 is obtained.

[0047] As another manufacturing method, instead of pouring molten resin directly into the molds 31 and 32, a resin film (not shown) may be provided on the first mold 31 side before pouring the molten resin. By using this method, a key top which has a resin film layer on the resin key top surface is obtained.

[0048] Here, examples which are different from the above embodiments of the present invention will also be described. For example, as in the case of an injection mold 43 as shown in cross section in Fig. 11, a swollen portion 45 is simply formed in order that the flange portion 44 of the resin key top can be removed beforehand to form the clearance portion 20 as in the above embodiment. As a result, it is rather hard for molten resin to flow through that portion, and air is gathered at a number of places around the swollen portion 45 (especially in the corner portions thereof) as indicated at 46, resulting in a deterioration in the quality of the resin key top obtained. Thus, with this mold 43 and a manufacturing method using the same, it is rather difficult to form the resin key top 13 of the above-described embodiments or other embodiments of the present invention.

Example

[0049] Next, the present invention will be described with reference to specific examples, which should not be construed restrictively.

Example 1

[0050] As the mold for molding the resin key tops (13) of polycarbonate resin for a mobile phone, the first mold (31) of hard iron for molding the front side of the resin key tops (13) and the second mold (32) of hard iron for molding the back side of the resin key tops (13) were prepared, as shown in Figs. 5 and 6. When mated with each other, the first mold (31) and the second mold (32) define the cavity composed of the key top forming portion (34) having in the outer periphery of the lower end of the side surface thereof an outwardly protruding flange portion (39), the first runner portion (33), and the second runner portion (35). Further, the molding pin (41) of hard iron was inserted into the pin insertion hole (42) of the first mold to thereby form inside the cavity the column-like resin relief protrusion (38).

[0051] Molten polycarbonate resin was injected into the cavity through the resin injection hole (36) of the second mold (32), and after its solidification, the resin was released from the mold to obtain the molded piece. Next, the portions corresponding to the first runner portion (33) and the second runner portion (32) were removed by using a cutting die to obtain the resin key top (13) of polycarbonate resin having the arcuate clearance portion (20) in a part of the flange portion (18) thereof. This resin key top (13) had a height of 2 mm, and exhibited the flange portion (18) protruding outwardly by 0.2 to 0.5 mm from the lower end of the side surface of the resin key top (13) and having a thickness of 0.15 to 0.3 mm.

[0052] In this method of manufacturing the resin key top (13), the molding pin (41) is inserted into the cavity of the injection mold, at the position corresponding to the clearance portion (20) formed on the flange portion (18), to provide the resin relief protrusion (38), so that, solely by removing the portions corresponding to the runner portions (33, 35) by using a cutting die, the clearance portion (20) could be easily formed. Further, flow marks due to the flow of molten resin were to be observed in none of the portions of the resin key top (13) including the flange portion (18):

[0053] A polycarbonate type ink was applied by screen printing to the flange portion (18) of the resin key top (13) to form a shielding layer (not shown), and then this resin key top (13) was glued by means of ultraviolet setting type adhesive (with a thickness of 0.05 mm) to the key sheet (12) formed of translucent silicone rubber and having the accommodating portion (19) protruding by 0.5 mm at the position where it covers the chip component (16) to thereby obtain the translucent key pad (11). When combined with the substrate (17) and illuminated from the chip component (16) with an LED incorporated there-

in, this key pad (11) involved no light leakage through the gap between the resin key top (13) and the casing (21). Further, whether the resin key top (13) was being depressed or not, the flange portion (18) thereof did not come into contact with the chip component (16) or the accommodating portion (19) of the key sheet (12) covering the same.

Example 2

[0054] Instead of the mold used in Example 1, a mold (not shown), which differs from in a point that it had a resin relief protrusion on the first runner portion side and had no resin relief protrusion on the second runner portion side, was used to form a polycarbonate resin key top (13) in the same manner as in Embodiment 1.

[0055] As in Example 1, according to this method of manufacturing the resin key top (13), the resin key top (13) with the clearance portion (20) could be easily obtained solely by cutting off the portions corresponding to the first runner portion and the second runner portion by using the cutting die. However, some flow marks, which are seemingly attributable to the flow of molten polycarbonate resin from the first runner portion provided with the resin relief protrusion to the key top forming portion, were observed on the flange portion (18) and other portions of the resin key top (13).

Comparative Example 1

[0056] Using a mold (43) of a different construction from those of the ones used in the above example, a resin key top was prepared. As shown in Fig. 11, in the mold (43), a swollen portion (45) for forming the clearance portion was formed at a corner of the flange portion (44) where no runner portion was provided, and a resin relief protrusion was provided in none of the runner portions. In the same manner as in Example 1, a polycarbonate resin molded piece was obtained by using this mold (43).

[0057] According to this resin key top manufacturing method, the molded piece obtained through the manufacturing process involved generation of a number of air gatherings (46) on both ends of the clearance portion formed at the flange portion (44), as shown in Fig. 11.

[0058] In the key pad of the present invention and the resin key top used therein, the resin key top has a clearance portion of a configuration in conformity with the interference member, so that, even in the case of a key pad reduced in thickness and size, it is possible to prevent the resin key top from coming into contact with the interference member. Further, no light leakage occurs when illumination is effected by means of an LED or the like.

[0059] Further, in the resin key top injection mold of the present invention, there is formed in the cavity a resin relief protrusion having a molding surface swollen from the entrance of the key top forming portion for forming the resin key top and the runner portion forming a portion to be disposed of toward the key top forming portion side,

is narrower than the entrance and exhibits a configuration in conformity with the outer configuration of the interference member at least the upper portion of which is situated in the displacement region of the bottom surface edge of the resin key top to be displaced upon depression. Consequently, variation in the size and configuration of the clearance portion among the resin key tops is eliminated, and it is possible to easily obtain a resin key top reduced in thickness and size and eliminating light leakage.

[0060] Further, according to the resin key top manufacturing method of the present invention, by using a predetermined mold, it is possible to easily form on the resin key top side surface, solely by the usual runner portion eliminating process, a clearance portion of a configuration in conformity with the outer configuration of the interference member at least the upper portion of which at least the upper portion is situated in the displacement region of the bottom surface edge of the resin key top to be displaced upon depression. Further, it is possible to obtain a high quality resin key top which is free from flow marks or air gathering and improved in terms of yields in a stable manner.

Claims

1. A pushbutton switch device comprising:

a key pad having a plurality of resin key tops (13) arranged on a translucent key sheet (12); and
a substrate (17) which is arranged below the key pad and on which a circuit component (16) is mounted, the circuit component (16) protruding from a surface of the substrate (17),
the resin key tops (13) being adapted to be pressed toward the substrate (17) to effect an input operation with the resin key tops (13),

characterized in that

the circuit component (16) of the substrate (17) is mounted to the substrate (17) at a position between adjacent resin key tops (13) arranged on the key pad, each of the resin key tops (13) of the key pad having an outwardly protruding flange portion (18) formed at a lower end of its side surface, and wherein the flange portion (18) has a recessed portion (20) adapted to prevent contact with the circuit component (16) upon depression of the resin key tops (13).

2. A pushbutton switch device according to Claim 1,

characterized in that

the circuit component has a height such that the circuit component protrudes from a surface of the key sheet (12).

3. A pushbutton switch device according to claim 1, wherein the key sheet (12) of the key pad has an accommodation portion (19) protruding from a surface thereof, the accommodation portion (19) accommodating the circuit component (16).
4. A pushbutton switch device according to claim 1, wherein the key sheet (12) of the key pad has a leg portion (17c) that floatingly supports a resin key top (13) mounting portion of the key sheet (12) such that the leg portion is capable of moving toward and away from the substrate (17).
5. A resin key top injection mold (31) adapted to mold a resin key top (13) according to claim 1, **characterized in that** the resin key top injection mold (31) comprises:
- a key top forming portion (34) having a flange portion (39) at an end portion thereof and a runner portion (33, 35) communicating with the key top forming portion (34), the key top forming portion (34) and the runner portion (33, 35) defining a cavity; and
 - a resin relief protrusion (38) formed at a boundary portion between the flange portion (39) and the runner portion (33, 35) and protruding from a cavity surface, the resin relief protrusion (38) being smaller in width than the boundary portion and having a molding surface that is convex toward the flange portion (39).
6. A resin key top injection mold (31) according to Claim 5, **characterized in that** the molding surface of the resin relief protrusion (38) has a configuration in conformity with an outer configuration of a circuit component (16) provided on a circuit board (17).
7. A resin key top injection mold (31) according to Claim 5, **characterized in that** the molding surface of the resin relief protrusion (38) has a configuration in conformity with an outer configuration of an accommodation portion (19) for a circuit component (16) which is formed in a key sheet (12).
8. A resin key top injection mold (31) according to any one of claims 5 through 7, **characterized in that** the resin relief protrusion (38) is formed by a pin member protruding into the cavity at the boundary portion, and wherein the resin key top injection mold (31) has a pin hole (42) allowing attachment and de-

tachment of the pin member.

9. A resin key top injection mold (32) serving as a second mold to be used with the resin key top injection mold (31) as recited in any one of Claims 5 through 8 which serves as a first mold, the resin key top injection mold (32) comprising an air vent portion (37) communicating with the runner portion (35) provided in the first mold.
10. A method of manufacturing a resin key top (13) according to claim 1 by using a resin key top injection mold (31), the resin key top (13) having an outwardly protruding flange portion (18) at a lower end of its side surface and a recessed portion (20) formed in the flange portion (18), the resin key top injection mold (31) having: a key top forming portion (34) having a flange portion (39) at an end portion thereof and a runner portion (33, 35) communicating with the key top forming portion (34), the key top forming portion (34) and the runner portion (33, 35) defining a cavity; and a resin relief protrusion (38) formed at a boundary portion between the flange portion (39) and the runner portion (33, 35) and protruding from a cavity surface, the resin relief protrusion (38) being smaller in width than the boundary portion and having a molding surface that is convex toward the flange portion (39), **characterized in that** the method comprises the steps of; obtaining a molded piece by pouring a molten resin into the cavity of the resin key top injection mold (31), allowing the molten resin to solidify to obtain a solidified resin, and releasing the solidified resin from the resin key top injection mold (31); removing the runner portion (35) from the molded piece; and forming the recessed portion (20) in the flange portion (18) such that the recessed portion (20) has a configuration in conformity with a configuration of the molding surface of the resin relief protrusion (38).
11. A method according to Claim 10, **characterized in that** the resin key top injection mold is the resin key top injection mold as recited in any one of Claims 5 to 8.

50 Patentansprüche

1. Drucktastenschalter, welcher folgendes aufweist:
- ein Tastenfeld, welches eine Vielzahl von Harztastenabdeckungen (13) aufweist, die auf einer lichtdurchlässigen Tastaturfolie (12) angeordnet sind; und
 - ein Substrat bzw. Trägermaterial, welches un-

terhalb des Tastenfeldes angeordnet ist und auf welchem ein Schaltungsbauteil (16) montiert ist, wobei das Schaltungsbauteil (16) von einer Oberfläche des Substrats (17) hervorsteht,

wobei die Harztastenabdeckungen (13) dafür vorgesehen sind, in Richtung des Substrats (17) gepresst zu werden, um eine Eingabe mit den Harztastenabdeckungen (13) zu bewirken,

dadurch gekennzeichnet, dass

das Schaltungsbauteil (16) des Substrats (17) an einer Position zwischen benachbarten, auf dem Tastenfeld angeordneten Harztastenabdeckungen (13) an dem Substrat (17) montiert ist,

wobei jede der Harztastenabdeckungen (13) des Tastenfeldes einen nach außen hervorstehenden Flanschabschnitt (18) aufweist, welcher an einem unteren Ende ihrer Seitenfläche gebildet ist, und wobei der Flanschabschnitt (18) einen ausgesparten Abschnitt (20) aufweist, welcher dafür vorgesehen ist, einen Kontakt mit dem Schaltungsbauteil (16) beim Drücken der Harztastenabdeckungen (13) zu verhindern.

2. Drucktastenschalter nach Anspruch 1,

dadurch gekennzeichnet, dass

das Schaltungsbauteil eine derartige Höhe aufweist, dass das Schaltungsbauteil von einer Oberfläche der Tastaturfolie (12) hervorsteht.

3. Drucktastenschalter nach Anspruch 1, wobei die Tastaturfolie (12) des Tastenfeldes einen Aufnahmeabschnitt (19) aufweist, welcher von einer Oberfläche derselben hervorsteht, wobei der Aufnahmeabschnitt (19) das Schaltungsbauteil (16) aufnimmt.

4. Drucktastenschalter nach Anspruch 1, wobei die Tastaturfolie (12) des Tastenfeldes einen Beinabschnitt (17c) aufweist, welcher einen Anbringungsabschnitt der Harztastenabdeckung (13) der Tastenfolie (12) derart schwimmend trägt, dass der Beinabschnitt in der Lage ist, sich in Richtung des Substrats (17) und weg von demselben zu bewegen.

5. Spritzgießwerkzeug für eine Harztastenabdeckung, welches dafür vorgesehen ist, eine Harztastenabdeckung (13) gemäß Anspruch 1 zu gießen,

dadurch gekennzeichnet, dass

das Spritzgießwerkzeug (31) für die Harztastenabdeckung folgendes aufweist:

einen Formabschnitt (34) für eine Tastenabdeckung, welcher einen Flanschabschnitt (39) an einem Endabschnitt desselben und einen Zulaufabschnitt (33,35) aufweist, welcher mit dem Formabschnitt (34) für die Tastenabdeckung in Verbindung steht, wobei der Formabschnitt (34) für die Tastenabdeckung und der Zulaufab-

schnitt (33,35) einen Hohlraum festlegen; und einen Harzentlastungsvorsprung (38), welcher an einem Grenzabschnitt zwischen dem Flanschabschnitt (39) und dem Zulaufabschnitt (33,35) gebildet ist und von einer Fläche eines Hohlraums hervorsteht, wobei der Harzentlastungsvorsprung (38) in der Breite kleiner als der Grenzabschnitt ist und eine Gießfläche aufweist, welche in Richtung des Flanschabschnitts (39) konvex ist.

6. Spritzgießwerkzeug (31) für eine Harztastenabdeckung nach Anspruch 5,

dadurch gekennzeichnet, dass

die Gießfläche des Harzentlastungsvorsprungs (38) eine Gestalt in Übereinstimmung mit einer äußeren Gestalt eines Schaltungsbauteils (16) aufweist, welches auf einer Leiterplatte (17) vorgesehen ist.

7. Spritzgießwerkzeug (31) für eine Harztastenabdeckung nach Anspruch 5,

dadurch gekennzeichnet, dass

die Gießfläche des Harzentlastungsvorsprungs (38) eine Gestalt in Übereinstimmung mit einer äußeren Gestalt eines Aufnahmeabschnitts (19) für ein Schaltungsbauteil (16) aufweist, welcher in einer Tastaturfolie (12) gebildet ist.

8. Spritzgießwerkzeug (31) für eine Harztastenabdeckung nach einem der Ansprüche 5 bis 7,

dadurch gekennzeichnet, dass

der Harzentlastungsvorsprung (38) durch ein Zapfenelement gebildet ist, welches an dem Grenzabschnitt in den Hohlraum ragt, und wobei das Spritzgießwerkzeug (31) für die Harztastenabdeckung eine Zapfenbohrung (42) aufweist, welche ein Anbringen und ein Abnehmen des Zapfenelements ermöglicht.

9. Spritzgießwerkzeug (32) für eine Harztastenabdeckung, welches als ein zweites Gießwerkzeug dient, das mit dem Spritzgießwerkzeug (31) für die Harztastenabdeckung nach einem der Ansprüche 5 bis 8, das als ein erstes Gießwerkzeug dient, zu verwenden ist, wobei das Spritzgießwerkzeug (32) für die Harztastenabdeckung, einen Entlüftungsöffnungsabschnitt (37) aufweist, welcher mit dem in dem ersten Gießwerkzeug vorgesehenen Zulaufabschnitt (35) in Verbindung steht.

10. Verfahren zum Herstellen einer Harztastenabdeckung (13) nach Anspruch 1 unter Verwendung eines Spritzgießwerkzeugs (31) für die Harztastenabdeckung,

wobei die Harztastenabdeckung (13) einen nach außen überstehenden Flanschabschnitt (18) an einem unteren Ende seiner Seitenfläche und einen ausgesparten Abschnitt (20) aufweist, der in dem Flansch-

abschnitt (18) gebildet ist,
 wobei das Spritzgießwerkzeug (31) für die Harztastenabdeckung folgendes aufweist: einen Formabschnitt (34) für eine Tastenabdeckung, welcher einen Flanschabschnitt (39) an einem Endabschnitt desselben, und einen Zulaufabschnitt (33,35) aufweist, welcher mit dem Formabschnitt (34) für die Tastenabdeckung in Verbindung steht, wobei der Formabschnitt (34) für die Tastenabdeckung und der Zulaufabschnitt (33,35) einen Hohlraum festlegen; und einen Harzentlastungsvorsprung (38), welcher an einem Grenzabschnitt zwischen dem Flanschabschnitt (39) und dem Zulaufabschnitt (33,35) gebildet ist und von einer Fläche eines Hohlrums hervorsteht, wobei der Harzentlastungsvorsprung (38) in der Breite kleiner als der Grenzabschnitt ist und eine Gießfläche aufweist, welche in Richtung des Flanschabschnitts (39) konvex ist,
dadurch gekennzeichnet, dass
 das Verfahren die folgenden Schritte aufweist:

Erlangen eines gegossenen Teils durch Gießen eines geschmolzenen Harzes in den Hohlraum des Spritzgießwerkzeugs (31) für die Harztastenabdeckung, wobei es dem geschmolzenen Harz ermöglicht wird, zu erstarren, um ein erstarrtes Harz zu erlangen, und wobei das erstarrte Harz aus dem Spritzgießwerkzeug (31) für die Harztastenabdeckung entformt wird;
 Entfernen des Zulaufabschnitts (35) von dem gegossenen Teils, und
 Bilden des ausgesparten Abschnitts (20) in dem Flanschabschnitt (18), so dass der ausgesparte Abschnitt (20) eine Gestalt in Übereinstimmung mit einer Gestalt der Gießfläche des Harzentlastungsvorsprungs (38) aufweist.

11. Verfahren nach Anspruch 10,
dadurch gekennzeichnet, dass
 das Spritzgießwerkzeug für die Harztastenabdeckung das Spritzgießwerkzeug für die Harztastenabdeckung nach einem der Ansprüche 5 bis 8 ist.

Revendications

1. Commutateur à boutons-poussoirs comprenant:

un clavier comportant plusieurs dessus de touches en résine (13) ménagées sur un film de touche translucide (12); et
 un substrat (17) qui est ménagé en dessous du clavier et sur lequel un composant de circuit (16) est monté, le composant de circuit (16) dépassant d'une surface du substrat (17),
 les dessus de touches en résine (13) étant agencés pour être appuyés vers le substrat (17) pour effectuer une opération d'entrée avec les

dessus de touches en résine (13),

caractérisé en ce que

le composant de circuit (16) du substrat (17) est monté sur le substrat (17) entre des dessus de touches en résine (13) adjacentes ménagées sur le clavier, chacun des dessus de touches en résine (13) du clavier ayant un rebord (18) dépassant vers l'extérieur formé à une extrémité inférieure de sa surface latérale, et
 dans lequel le rebord (18) a une partie évidée (20) agencée pour empêcher un contact avec le composant de circuit (16) lors d'un enfoncement des dessus de touches en résine (13).

2. Commutateur à boutons-poussoirs selon la revendication 1,

caractérisé en ce que

le composant de circuit a une hauteur telle que ledit composant de circuit dépasse d'une surface du film de touches (12).

3. Commutateur à boutons-poussoirs selon la revendication 1, dans lequel

le film de touches (12) du clavier comporte un logement (19) dépassant d'une de ses surfaces, le logement (19) logeant le composant de circuit (16).

4. Commutateur à boutons-poussoirs selon la revendication 1, dans lequel

le film de touches (12) du clavier comporte un pied (17c) qui supporte de manière flottante une partie de montage d'un dessus de touche en résine (13) du film de touches (12) afin que le pied soit capable de se rapprocher ou de s'éloigner du substrat (17).

5. Moule d'injection (31) pour dessus de touche en résine agencé pour mouler un dessus de touche en résine (13) selon la revendication 1,

caractérisé en ce que

le moule d'injection (31) pour dessus de touche en résine comprend:

une partie de formage (34) d'un dessus de touche comportant un rebord (39) à une de ses parties d'extrémité et un canal d'alimentation (33, 35)

communiquant avec la partie de formage (34) du dessus de touche, la partie de formage (34) du dessus de touche et le canal d'alimentation (33, 35) définissant une cavité; et

une protubérance en relief en résine (38) formée à une partie limite entre le rebord (39) et le canal d'alimentation (33, 35) et dépassant d'une surface de la cavité, la protubérance en relief de résine (38) étant plus petite en largeur que la partie limite et ayant une surface de moulage qui est convexe vers le rebord (39).

6. Moule d'injection (31) pour dessus de touche en résine selon la revendication 5
caractérisé en ce que
la surface de moulage de la protubérance en relief de résine (38) a une configuration en conformité avec une configuration extérieure d'un composant de circuit (16) disposé sur une carte de circuit (17). 5
7. Moule d'injection (31) pour dessus de touche en résine selon la revendication 5
caractérisé en ce que
la surface de moulage de la protubérance en relief de résine (38) a une configuration en conformité avec une configuration extérieure d'un logement (19) pour un composant de circuit (16) qui est formé dans un film de touche (12). 10 15
8. Moule d'injection (31) pour dessus de touche en résine selon l'une quelconque des revendications 5 à 7,
caractérisé en ce que
la protubérance en relief de résine (38) est formée par une goupille faisant saillie dans la cavité à la partie limite, et dans lequel le moule d'injection (31) pour dessus de touche en résine comporte un trou de goupille (42) permettant l'attachement et la séparation de la goupille. 20 25
9. Moule d'injection (32) pour dessus de touche en résine servant de second moule devant être utilisé avec le moule d'injection (31) pour dessus de touche en résine tel qu'exposé dans l'une quelconque des revendications 5 à 8, qui sert de premier moule, le moule d'injection (32) pour dessus de touche en résine comportant un évent d'air (37) communiquant avec le canal d'alimentation (35) ménagé dans le premier moule. 30 35
10. Procédé de fabrication d'un dessus de touche en résine (13) selon la revendication 1 en utilisant un moule d'injection (31) pour dessus de touche en résine,
le dessus de touche en résine (13) ayant un rebord (18) dépassant vers l'extérieur à l'extrémité inférieure de sa surface latérale et une partie évidée (20) formée dans le rebord (18),
le moule d'injection (31) pour dessus de touche en résine ayant: une partie de formage (34) d'un dessus de touche comportant un rebord (39) à une de ses parties d'extrémité et un canal d'alimentation (33, 35) communiquant avec la partie de formage (34) du dessus de touche, la partie de formage (34) du dessus de touche et le canal d'alimentation (33, 35) définissant une cavité; et une protubérance en relief en résine (38) formée à une partie limite entre le rebord (39) et le canal d'alimentation (33, 35) et dépassant d'une surface de la cavité, la protubérance en relief de résine (38) étant plus petite en largeur 40 45 50 55

que la partie limite et ayant une surface de moulage qui est convexe vers le rebord (39).

caractérisé en ce que

le procédé comprend les étapes consistant en:

l'obtention d'une pièce moulée par coulage d'une résine fondue dans la cavité du moule d'injection (31) pour dessus de touche en résine, permettant à la résine fondue de se solidifier pour obtenir une résine solidifiée, et libération de la résine solidifiée du moule d'injection (31) pour dessus de touche en résine; le retrait du canal d'alimentation (35) de la pièce moule; et la formation de la partie évidée (20) dans le rebord (18) afin que la partie évidée (20) ait une configuration en conformité avec une configuration de la surface de moulage de la protubérance en relief de résine (38).

- 20 11. Procédé selon la revendication 10,

caractérisé en ce que

le moule d'injection pour dessus de touche en résine est le moule d'injection pour dessus de touche en résine tel qu'exposé dans l'une quelconque des revendications 5 à 8

Fig.1

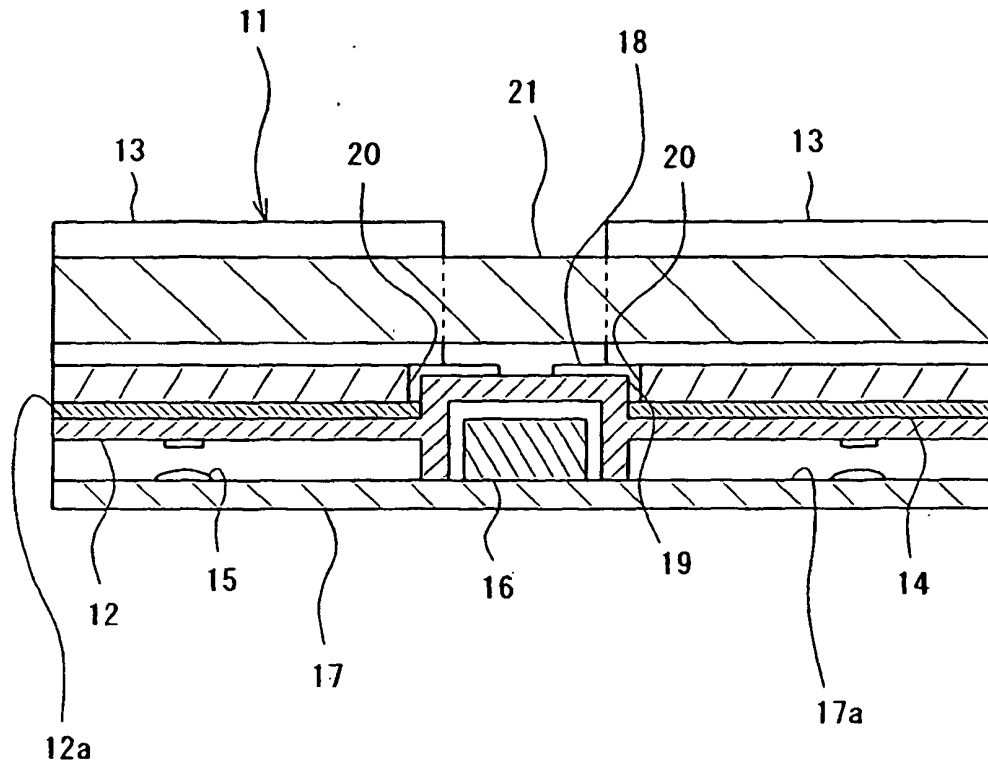


Fig.2

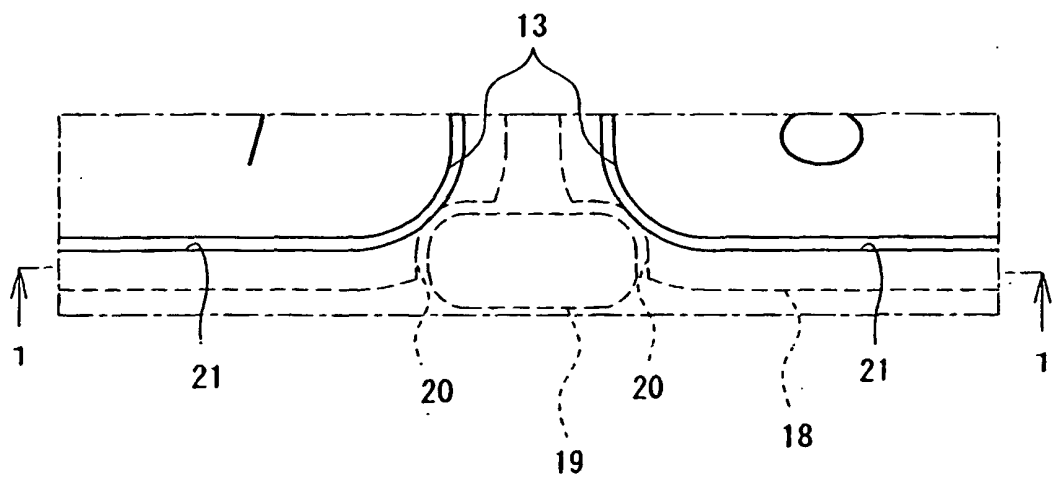


Fig.3

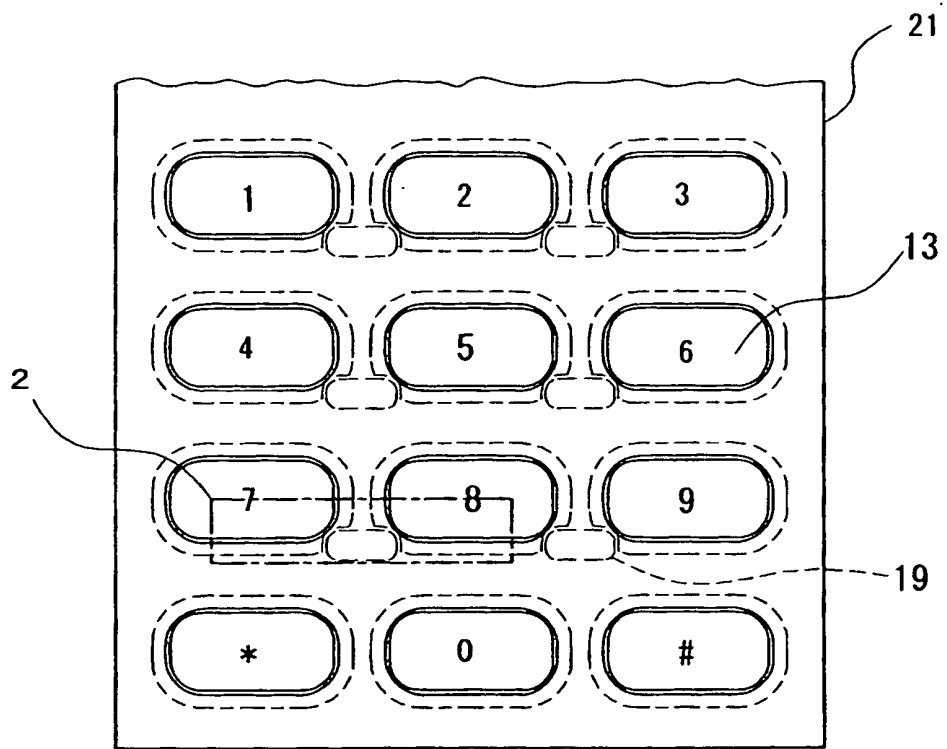


Fig.4

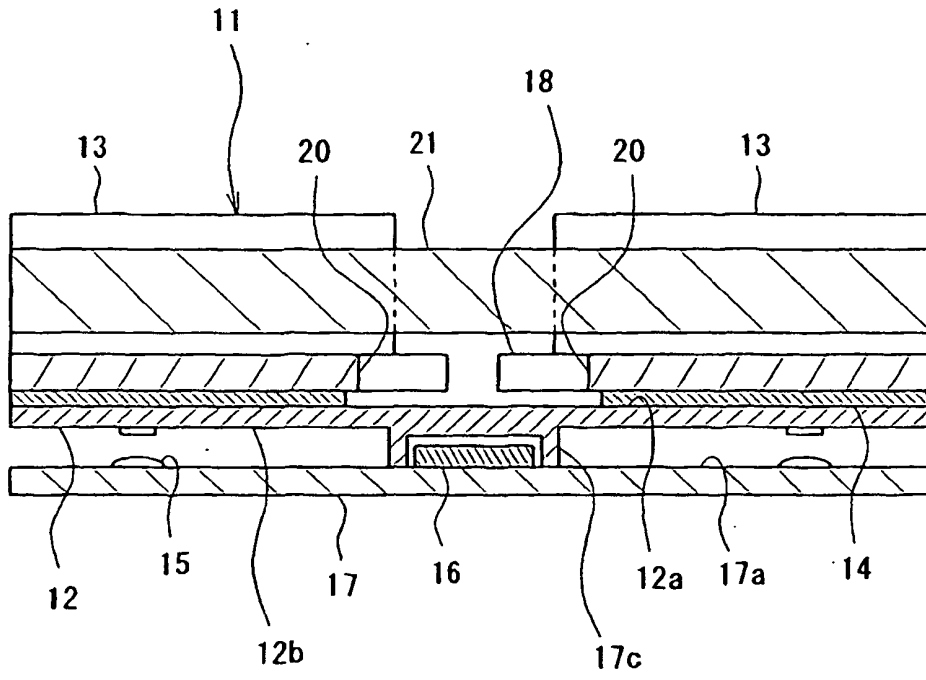


Fig.5

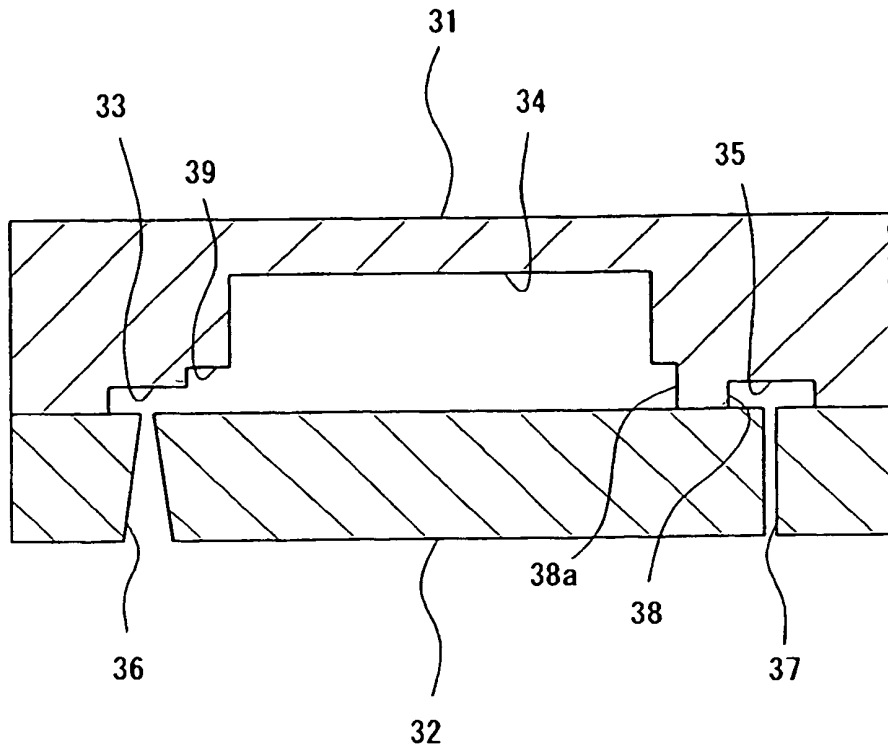


Fig.6

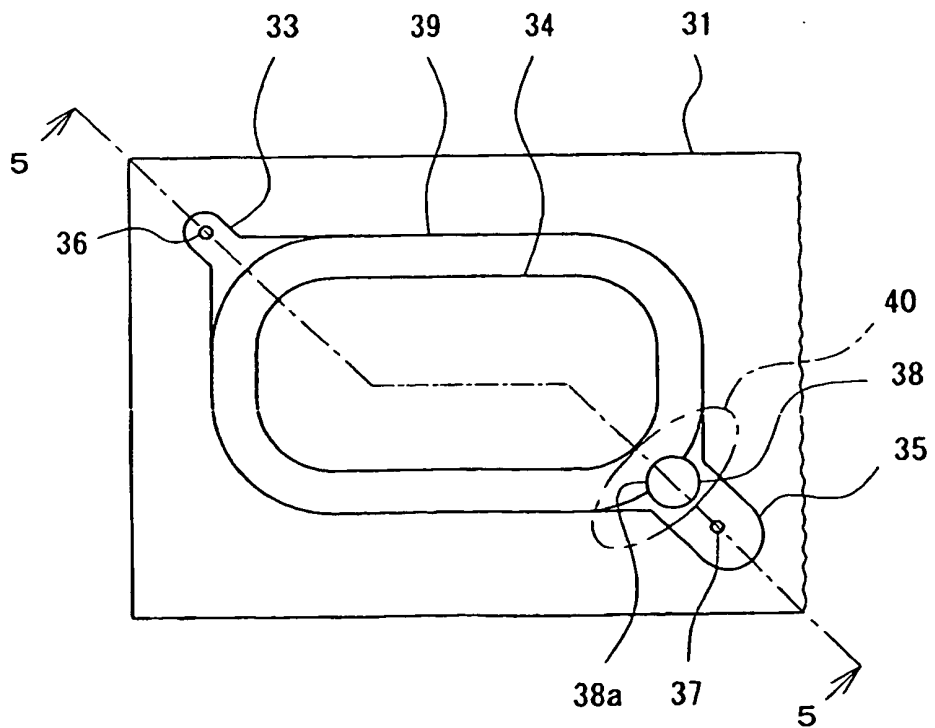


Fig.7

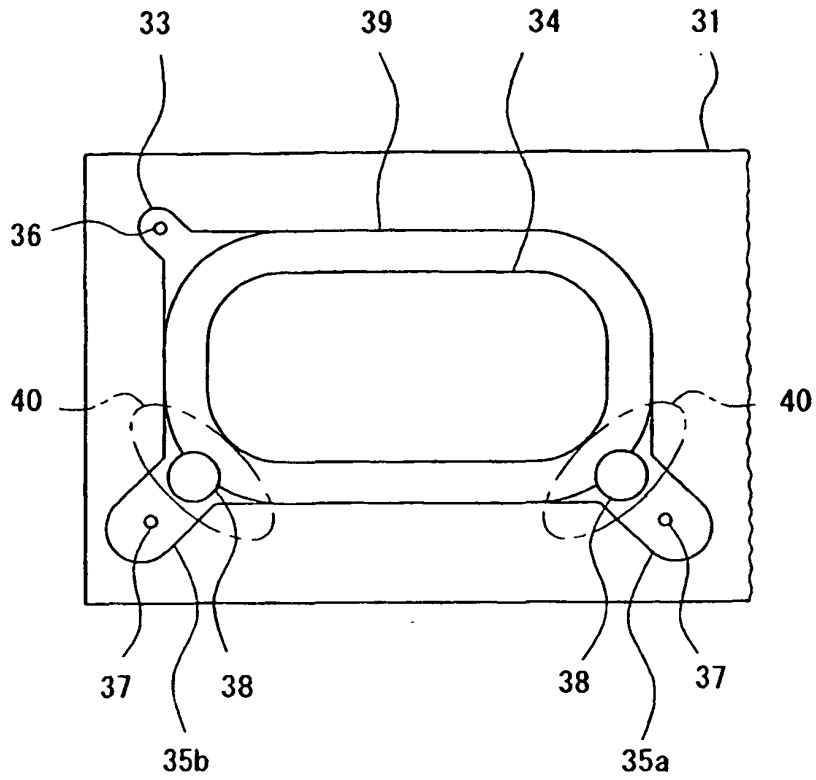


Fig.8

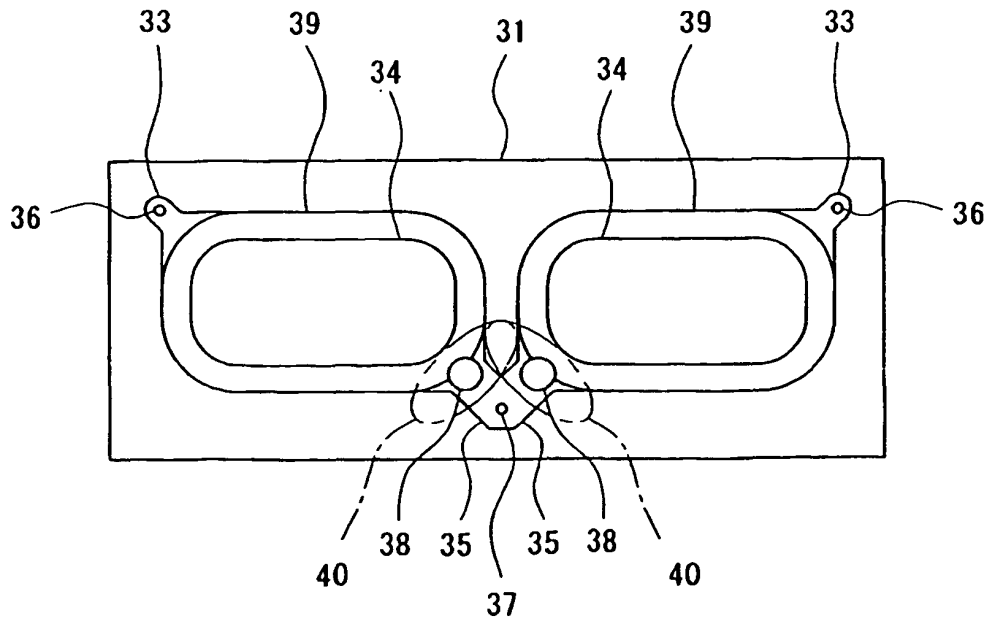


Fig.9

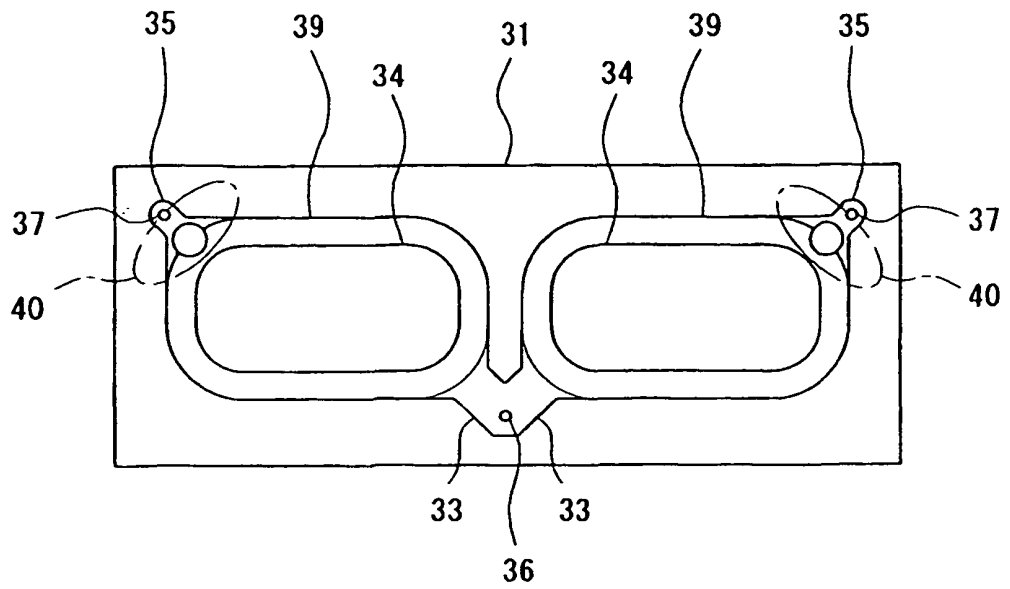


Fig.10

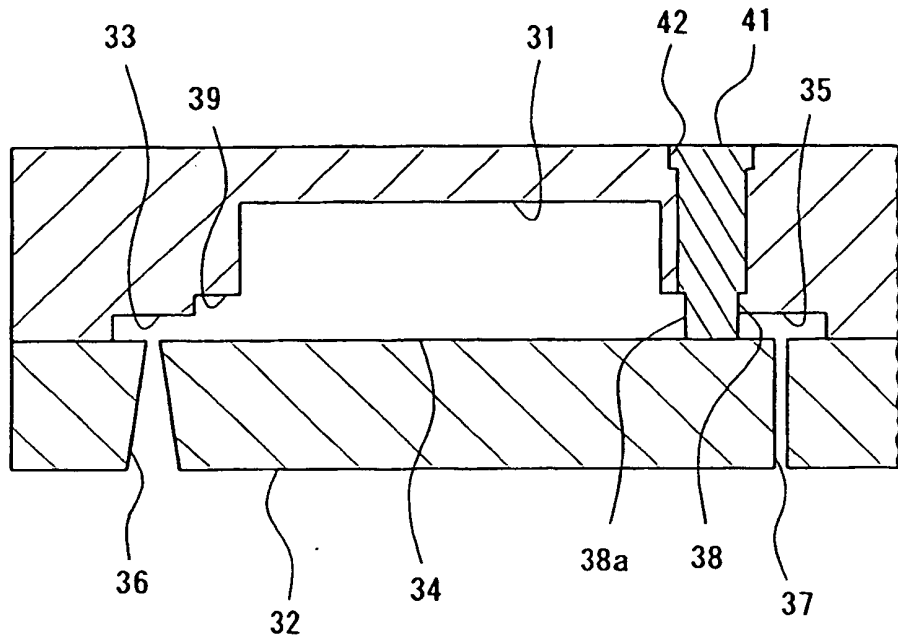


Fig.11

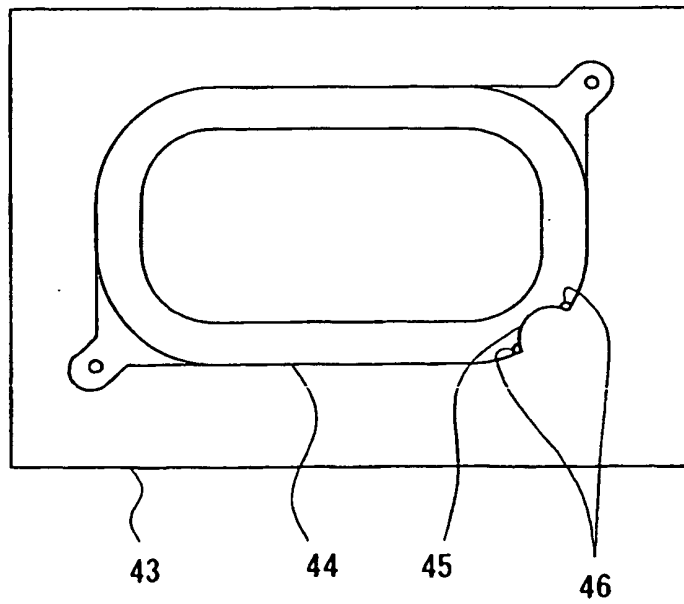


Fig.12 (Prior Art)

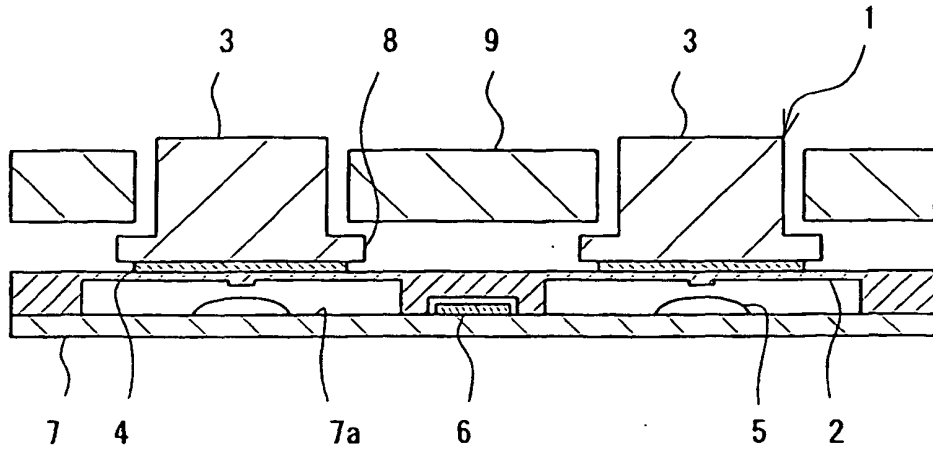


Fig.13 (Prior Art)

